

# Exhibit B

02FEB 6.1998 1-4:16PM 1 BELLER, INDY

KB ELECTRONICS INC

NO. 156 P. 2/2

001

Sheet 1

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Environment	Bare	Air	Nitrogen	Ultrasonic
X Dimension	0.159	0.21	0.225	0.24
Y Dimension	0.159	0.229	0.239	0.281
Thickness PC3	0	0.0609	0.0612	0.0603
Thickness Reformed	0.088	0.07	0.067	0.067
Finished Thickness	0.088	0.0591	0.0588	0.0632
Area	0.01906	0.03777	0.03355	0.03912
Volume				
% Area Increase	0	0.992	1.697	2.481
Process				
Dip Volume bath of Solder Paste M/Metrics NC-73 repeat flux				
Deposit tab flux side down onto bare copper coupon coated with Entek CL-106A				
Reflow under air for 120 seconds				
Reflow under air with Ultrasonic for 90 seconds				
Reflow in Nitrogen in 10 Zone reflow furnace				
Ultrasonic: Rubber band onto Ultrasonic horn and heat using a Chiselacter with ~1/4" clearance from nozzle				

Best Available Copy